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Amendment
Attorney Docket No. 011.2B-11481-US01

dioxide and a portion including polycrystalline silicon, the polishing composition consisting of water, water-soluble amine, and a component other than water and water-soluble amine, wherein the water-soluble amine comprises at least one of triethylenetetramine and tetraethylenepentamine and is dissolved in the water, and the component other than water and water-soluble amine is not present in a solid state in the polishing composition.

16. (New) The polishing composition according to claim 15, wherein the component other than water and water-soluble amine is a surface-active agent.

COMMENTS*Claim Objections*

Claim 2 has been canceled to address the claim objections.

Claim Rejections – 35 USC § 102

Independent claim 1 recites a polishing composition consisting of water and water-soluble amine. Independent claim 15 recites a polishing composition consisting of water, water-soluble amine, and a component other than water and water-soluble amine, wherein the component other than water and water-soluble amine is not present in a solid state in the polishing composition. That is, a polishing composition of the claimed invention is an aqueous solution, which does not contain solid matter that is present in a solid state in the polishing composition. Thus, according to a polishing composition of the claimed invention, no defects occur from solid matter contained in the polishing composition. Furthermore, there is no need to separate solid matter from the polishing composition before the polishing composition is disposed of.

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Contrastingly, a polishing composition of Wang et al. US 6,855,266 ("Wang") does not exclude containing solid matter that is present in a solid state in the polishing composition. Accordingly, if a person skilled in the art prepares a polishing composition usable in polishing an object having a portion including silicon dioxide and a portion including polycrystalline silicon based on Wang, solid matter may be contained in the prepared polishing composition. A polishing composition that contains solid matter is not usable in polishing an object having a portion including silicon dioxide and a portion including polycrystalline silicon (see examples and comparative examples of the present application).

Since the claimed invention provides notable knowledge in the art and is not apparent from Wang, the claimed invention should be patentable over Wang.

Further, the examiner alleges that "Wang discloses a polishing composition consisting of water and water-soluble amine comprises tetraethylenepentamine at the concentration of 0.21 wt% (See Table 3 Control# 3E)". This is not true. The polishing composition of System 3E at least contains 3 wt% alumina as well as tetraethylenepentamine. See line 63 in column 13 to line 13 in column 14. That is, Wang merely discloses a polishing composition comprising water and tetraethylenepentamine, but does not disclose a polishing composition consisting of water and tetraethylenepentamine, as recited in claim 1 as amended.

Newly Added Claims

Support for new claims 13 and 14 can be found at lines 12 to 18 on page 5 in the specification. Support for new claims 15 and 16 can be found at lines 12 to 16 on page 8 in the specification. Therefore, no new matter has been added.

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This Amendment is in response to the Office Action dated February 14, 2006.

Respectfully submitted,

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Date: August 14, 2006

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